

L Number	Hits	Search Text	DB	Time stamp
-	129	(partial adj processing or selective adj processing) and semiconductor adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:19
-	3	o-ring and ((partial adj processing or selective adj processing) and semiconductor adj wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 10:47
-	96	processing adj chuck	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 10:46
-	17	o-ring and (processing adj chuck)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 10:53
-	15	partial adj wafer adj processing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:04
-	0	mobil adj chamber and semiconductor adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:04
-	1	mobile adj chamber and semiconductor adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:05
-	8	micro adj chamber and semiconductor adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:07
-	435	(451/39).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:10
-	794	(118/720).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:34
-	10	4676193.URPN.	USPAT	2004/06/23 11:26
-	0	"partically covering the substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:34
-	0	"partially covering the substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:34
-	0	"partlly covered substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:36

-	10	"partially covered substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:37
-	2	micro adj process adj chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:47
-	6	5997963.URPN.	USPAT	2004/06/23 11:39
-	5	(micro adj process adj chamber or micro adj chamber) and (air adj bearing or gas adj bearing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:48
-	6	5997963.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 11:48
-	12	("4704348"   "4801352"   "5025284"   "5087927"   "5103102"   "5559584"   "5877843"   "5973764"   "5997963"   "6208406"   "6313953"   "6538716"   "2002/0145711"   "2003/0006380").PN.	USPAT	2004/06/23 11:50
-	7	("4778745"   "5428442"   "5838951"   "5851848"   "5943551"   "6016358"   "6028664").PN.	USPAT	2004/06/23 12:03
-	0	6216055.URPN.	USPAT	2004/06/23 12:07
-	448	(differential adj pumped or differentially adj pumped or differential adj pumping) and portion and (wafer or substrate) and (process or processing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:12
-	211	thin adj film and ((differential adj pumped or differentially adj pumped or differential adj pumping) and portion and (wafer or substrate) and (process or processing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:23
-	921	noji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:23
-	78	chamber and noji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:30
-	969	ebara adj corporation.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:31
-	2	((differential adj pumped or differentially adj pumped or differential adj pumping) and portion and (wafer or substrate) and (process or processing)) and (ebara adj corporation.as.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/23 12:31
-	750	(438/758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:23
-	42	o-ring and ((438/758).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:20

-	149	(438/765).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:26
-	38	mobile adj workpiece	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:30
-	0	minature adj process adj chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:31
-	2	micro adj process adj chamber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:40
-	2	("6764386").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:43
-	6	("4987286"   "5202008"   "5898179"   "5921560"   "5931721"   "6056632"   "2001/0055937"   "2004/0009738"   "2004/0029494").PN.	USPAT	2004/11/04 16:41
-	6	((20010055937) or ("20040009738") or ("20040029494")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 16:43
-	6	("4987286"   "5202008"   "5898179"   "5921560"   "5931721"   "6056632"   "2001/0055937"   "2004/0009738"   "2004/0029494").PN.	USPAT	2004/11/04 16:44
-	0	6764386.URPN.	USPAT	2004/11/04 16:45
-	927	(118/729).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 17:17
-	2958	(427/248.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 17:18
-	117	o-ring and ((427/248.1).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 17:23
-	750	(438/758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 17:22
-	42	o-ring and ((438/758).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 17:23